

		APPLICATION FOR EXTENSION OF ESCC QUALIFICATION APPROVAL			Page 1
		Component Title: Integrated Circuits, Silicon, Monolithic, 35KLUT Radiation-Hardened FPGA (NG-Medium CQFP-352)	Executive Member: CNES	Date: 19/02/2025	Appl. No. 382A
Components (including series and families) submitted for Extension of Qualification Approval:					1
ESCC COMPONENT NO.	VARIANTS	RANGE OF COMPONENTS	BASED ON	TEST VEHICLE / S	COMPONENT SIMILAR
9304/010 issue 4	01	Integrated Circuits, Silicon Monolithic, 35KLUT Radiation-Hardened FPGA	ST C65SPACE ASIC platform technology	NX1H35AS in CQFP-352 package (NG-MEDIUM)	
Component Manufacturer		Location of Manufacturing Plant(s)		Date of original qualification approval:	
NanoXplore		NanoXplore (design) ST Crolles (foundry) Chipbond Taiwan (OPM (Over Pad Metallization)) ST Rennes (assembly) ST Grenoble (test) ST Grenoble + ST Rennes (space qualification)		Date: 31/08/2022 Certificate Ref No. 382	
ESCC Specifications used for Maintenance of qualification testing:		Deviations to LVT testing and Detail Specification used:		Qualification Extension Report reference and date:	
Generic: 9000 Issue: 11		No <input checked="" type="checkbox"/> Yes <input type="checkbox"/> (supply details in Box 15)		"VOQ_2022_2024_C65SPACE_NX1H35AS-v2.pdf" document and associated reports	
Detail(s): 9304/010 Issue: 4		Deviation from current Specifications: No <input checked="" type="checkbox"/> Yes <input type="checkbox"/> (Supply details)			
Summary of procurement or equivalent test results during current validity period in support of this application (those to ESCC listed first)					8
Project Name	Testing Level	LAT	Date code	Quantity Delivered	
PID changes since start of qualification		Current PID Verified by:		Name of Executive Representative	
None <input type="checkbox"/>		None		None	
Minor* <input checked="" type="checkbox"/>		ST012008 ESCC PID GENERIQUE (8097046.pdf)		Name of Executive Representative	
Major* <input type="checkbox"/>		PID for ASICs C65S WB and FC (DM00508779.pdf) ST Crolles PID (DM00408351.pdf) Chipbond Wafer Specification (DM00593640.pdf) Dice Layout PID (DM00508782.pdf)		Name of Executive Representative	
*Provide details in box:					
19					
Current Manufacturing facilities surveyed by: ESA and CNES on 12/07/2023					11
(Name of Executive Representative) (Date)					
Satisfactory: Yes <input checked="" type="checkbox"/> No <input type="checkbox"/> Explain MoM Quality Meeting held on the 12th of July 2023 (B2015)					
Report Reference: <u>CR-Activités ST Juillet 2023</u>					

	<p style="text-align: center;">APPLICATION FOR EXTENSION OF ESCC QUALIFICATION APPROVAL</p> <p>Component title: Integrated Circuits, Silicon, Monolithic, 35KLUT Radiation-Hardened FPGA (NG-Medium CQFP-352)</p> <p>Executive Member: CNES Date: 19/02/2025</p>	<p>Page 2</p> <p>Appl. No. 382A</p>
<p>Failure Analysis, DPA, NCCS available: Yes <input checked="" type="checkbox"/> No <input type="checkbox"/> (Supply data)</p> <p>Ref. No's and purposes: NCCS 2CSTM301 - ESA Logo – CLOSED NCCS 2CSTM401 - TID RAD LETTER MARKING – CLOSED NCCS 2CSTM402 - NG-Medium Qualified Flow Issue – CLOSED</p>		12
<p>The undersigned hereby certifies on behalf of the ESCC Executive - that the above information is correct; - that the appropriate documentation has been evaluated; - that full compliance to all ESCC requirements is evidence (except as stated in box 15;) - that the reports and data are available at the ESCC Executive and therefore applies on behalf of <u>CNES</u> as the responsible Executive Member for ESCC qualification status to be extended to the component(s) listed herein.</p> <p>Date: 19/02/2025</p> <p style="text-align: right;">  L. FONTAINE, CNES (Signature of the Executive Coordinator) </p>		13
<p>Continuation of Boxes above:</p> <p>Box 7:</p> <p>“VOQ_2022_2024_C65SPACE_NX1H35AS-v2.pdf” document and associated reports: 8097046.pdf (ESCC PID GENERIQUE) DM00508779.pdf (PID for ASICs C65S WB and FC) DM00408351.pdf (ST Crolles PID) DM00593640.pdf (Chipbond Wafer Specification) DM00508782.pdf (Dice Layout PID) esc9304010iss4.pdf (ESCC Detail Specification No. 9304/010) (NG-Medium Product) esc9202086iss2.pdf (ESCC Detail Specification No. 9202/086) (Technology Flow ST CMOS RH 65nm ASIC PLATFORM) DC2414A_SPCNGFPC532E_33220F0V01_SG1_SG3 - Chart F2 and F3: o 33220F0VRR_Chart_F2_F3.pdf o Electrical data (33229F0VRR): <ul style="list-style-type: none"> ▪ 33229F0VRR_Chart_F3_ElecData_FT1_AMBIANT.csv ▪ 33229F0VRR_Chart_F3_ElecData_FT1_HOT.csv ▪ 33229F0VRR_Chart_F3_ElecData_FT1_COLD.csv ▪ 33229F0VRR_Chart_F3_ElecData_BIA_AMBIANT.csv ▪ 33229F0VRR_Chart_F3_ElecData_BIH_HOT.csv ▪ 33229F0VRR_Chart_F3_ElecData_BIC_COLD.csv ▪ 33229F0VRR_Chart_F3_DriftReport.pdf o 33229F0V01_Chart_F2_F3.pdf o Electrical data: <ul style="list-style-type: none"> ▪ 33229F0V01_Chart_F3_ElecData_FT1_AMBIANT.csv ▪ 33229F0V01_Chart_F3_ElecData_FT1_HOT.csv ▪ 33229F0V01_Chart_F3_ElecData_FT1_COLD.csv ▪ 33229F0V01_Chart_F3_ElecData_BIA_AMBIANT.csv ▪ 33229F0V01_Chart_F3_ElecData_BIH_HOT.csv ▪ 33229F0V01_Chart_F3_ElecData_BIC_COLD.csv ▪ 33229F0V01_Chart_F3_DriftReport.pdf - Chart F4 (SG1 and SG3): o 33229F0V01_Chart_F4_SG1_SG3.pdf o Electrical data: <ul style="list-style-type: none"> ▪ 33229F0VRM_Chart_F4_ElecData_SG1_Environmental.csv ▪ 33229F0VRN_Chart_F4_ElecData_SG1_Mechanical.csv DC2309A_SPCNGFPC532E_33220F0VZX_SG2 - Chart F2 and F3: o 33220F0VZX_Chart_F2_F3.pdf o Electrical data: <ul style="list-style-type: none"> ▪ 33229F0VZX_Chart_F3_ElecData_FT1_AMBIANT.xlsx ▪ 33229F0VZX_Chart_F3_ElecData_FT1_HOT.xlsx ▪ 33229F0VZX_Chart_F3_ElecData_FT1_COLD.xlsx ▪ 33229F0VZX_Chart_F3_ElecData_BIA_AMBIANT.xlsx ▪ 33229F0VZX_Chart_F3_ElecData_BIH_HOT.xlsx ▪ 33229F0VZX_Chart_F3_ElecData_BIC_COLD.xlsx ▪ 33229F0VZX_Chart_F3_DriftReport.pdf - Chart F4 (SG2): o 33229F0VZX_Chart_F4_SG2.pdf o Electrical data: <ul style="list-style-type: none"> ▪ 33229F0VZQ_Chart_F4_ElecData_T0_Amb.csv ▪ 33229F0VZQ_Chart_F4_ElecData_T0_Hot.csv ▪ 33229F0VZQ_Chart_F4_ElecData_T0_Cold.csv ▪ 33229F0VZQ_Chart_F4_ElecData_500h_Amb.csv ▪ 33229F0VZQ_Chart_F4_ElecData_500h_Hot.csv ▪ 33229F0VZQ_Chart_F4_ElecData_500h_Cold.csv ▪ 33229F0VZQ_Chart_F4_ElecData_1000h_Amb.csv </p>		14

- 33229F0VZQ_Chart_F4_ElecData_1000h_Hot.csv
- 33229F0VZQ_Chart_F4_ElecData_1000h_Cold.csv
- 33229F0VZQ_Chart_F4_ElecData_2000h_Amb.csv
- 33229F0VZQ_Chart_F4_ElecData_2000h_Hot.csv
- 33229F0VZQ_Chart_F4_ElecData_2000h_Cold.csv
- 33229F0VZQ_Chart_F4_DriftReport.pdf

Sales listing.xlsx



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Component title: **Integrated Circuits, Silicon, Monolithic, 35KLUT Radiation-Hardened FPGA (NG-Medium CQFP-352)**

Executive Member: **CNES**

Date: **19/02/2025**

Page 3

Appl. No.

382A

Non compliance to ESCC requirements:

15

No.:	Specification	Paragraph	Non compliance

Additional tasks required to achieve full compliance for ESCC qualification or rationale for acceptability of noncompliance:

16

Executive Manager Disposition

17

Application Approval: Yes No

Action / Remarks:

Date: 31-03-2025

A. Zadeh: Head of Avionics and EEE Division,
Electrical Department



APPLICATION FOR EXTENSION OF ESCC QUALIFICATION APPROVAL

Page 4

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382A

ANNEX 1: LIST OF TESTS DONE TO SUPPORT EXTENSION OF QUALIFICATION

18

Tests conducted in compliance with:

- ESCC 9000 generic specification; Chart F4 (for ESCC/QPL parts);
- Or PID-TFD (for ESCC/QML parts)

Tests vehicle identification/description:

NX1H35AS CQFP-352 with Ceramic Tie Bar Gold Wire- Bonded	NX1H35AS has been designed in compliance with ST C65Space libraries and design rules for custom cells. The qualification has been performed with flight models from 1 diffusion lot. See "VOQ_2022_2024_C65SPACE_NX1H35AS-v2.pdf" document and associated reports
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Detail Specification reference: **9304/010**

NX1H35AS in CQFP-352 package :

Subgroup	Test	Tick when done	Conditions	Date Code Diffusion Lot	Tested Qty	No. of Rejects	Comments if not performed. Comments on Rejection
Environmental/Mechanical Subgroup	Thermal Shock	<input checked="" type="checkbox"/>	MIL-STD-883. Test Method 1011	NX1H35AS-CQFP352 Cut 1.2 Diffusion Lot: VQ128380 Assembly Lot: 33229F0VRM Date code: 2414A	15	0	
	Temperature Cycling	<input checked="" type="checkbox"/>	MIL-STD-883 Test Method 1010		15	0	
	Moisture Resistance	<input checked="" type="checkbox"/>	MIL-STD-883, Test Method 1004		15	0	
	Seal (Fine and Gross Leak)	<input checked="" type="checkbox"/>	MIL-STD-883, Test Method 1014		15	0	
	Intermediate and End-Point Electrical Measurements	<input checked="" type="checkbox"/>	Intermediate and End-Point Electrical Measurements in the Device Specification		12	0	For the Moisture resistance test, we are supposed to do it on components whose leads have been arched. To do this, we have to cut the tie bar of the CQFP352. The problem is that once we have cut the tie-bar, we are no longer able to do the electrical test in socket. So we indicated in §2.1.1.2 in esc9304010iss4.pdf (ESCC Detail Specification No. 9304/010) (NG-Medium Product) to arch the leads on 3 components instead of 15 and to switch to electrical testing only 12 parts with tie bar (same sampling and philosophy as in QML).
	External Visual Inspection	<input checked="" type="checkbox"/>	ESCC Basic Specification No. 20500 / 2059000		15	0	MIL-STD-883, Test Method 2009
	Mechanical Shock	<input checked="" type="checkbox"/>	MIL-STD-883, Test Method 2002	NX1H35AS-CQFP352 Cut 1.2 Diffusion Lot: VQ128380 Assembly Lot: 33229F0VRN Date code: 2414A	15	0	
	Vibration	<input checked="" type="checkbox"/>	MIL-STD-883, Test Method 2007		15	0	
	Constant Acceleration	<input checked="" type="checkbox"/>	MIL-STD-883, Test Method 2001		15	0	
	Seal (Fine and Gross Leak)	<input checked="" type="checkbox"/>	MIL-STD-883, Test Method 1014		15	0	
	Intermediate and End-Point Electrical Measurements	<input checked="" type="checkbox"/>	Intermediate and End-Point Electrical Measurements in the Device Specification		15	0	
	External Visual Inspection	<input checked="" type="checkbox"/>	ESCC Basic Specification No. 20500 / 2059000		15	0	MIL-STD-883, Test Method 2009

Subgroup	Test	Tick when done	Conditions	Date Code Diffusion Lot	Tested Qty	No. of Rejects	Comments if not performed. Comments on Rejection
Assembly Capability Subgroup	Permanence of Marking	<input checked="" type="checkbox"/>	ESCC Basic Specification No. 24800		NA	NA	Not Applicable on Laser Marking
	Terminal Strength	<input checked="" type="checkbox"/>	MIL-STD-883, Test Method 2004 Cond. B2	NX1H35AS-CQFP352 Cut 1.2 Diffusion Lot: VQ128380 Assembly Lot: 33229F0VRP Date code: 2414A	3	0	As described in §2.1.1.2 (a) in esc9304010iss4.pdf (ESCC Detail Specification No. 9304/010) (NG-Medium Product)
	Internal Visual Inspection	<input checked="" type="checkbox"/>	ESCC Basic Specification No. 2049000		5	0	MIL-STD-883 Test Method 2010A
	Bond Strength	<input checked="" type="checkbox"/>	MIL-STD-883 Test Method 2011		5	0	
	Die Shear	<input checked="" type="checkbox"/>	MIL-STD-883 Test Method 2019		4	0	

Subgroup	Test	Tick when done	Conditions	Date Code Diffusion Lot	Tested Qty	No. of Rejects	Comments if not performed. Comments on Rejection
Endurance Subgroup	Operating Life	<input checked="" type="checkbox"/>	MIL-STD-883, Test Method 1005	NX1H35AS-CQFP352 Cut 1.2 Diffusion Lot: VQ128380 Assembly Lot: 33229F0VZQ Date code: 2309A 2000h @125°C @Ta = +25°C @Tj Max = +125°C @Tc = -55°C Vccmax	15	0	
	Intermediate and End-Point Electrical Measurements	<input checked="" type="checkbox"/>	Intermediate and End-Point Electrical Measurements in the Device Specification		15	0	
	Seal (Fine and Gross Leak)	<input checked="" type="checkbox"/>	MIL-STD-883, Test Method 1014		15	0	
	External Visual Inspection	<input checked="" type="checkbox"/>	ESCC Basic Specification No. 2059000		15	0	MIL-STD-883, Test Method 2009



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Page 6
Appl. No.
382A

NOTES ON THE COMPLETION OF THE APPLICATION FORM FOR ESCC QUALIFICATION EXTENSION APPROVAL

ENTRIES

- Form heading shall indicate: - the title of the component as given in its detail specification or the name of the series, family; - the Executive Member; - the entering date; - the certificate number and its sequential suffix.
- Box 1** shall provide details given in the table; in particular there shall be listed: - the variants or range of variants; - the range of components (the ESCC code is recommended to indicate the values or values range, the tolerance, the voltage, etc); the designation given in the detail specification as 'base on'; - under Test Vehicle enter either an ESCC code or the specific characteristic capable of identifying the component tested (e.g., voltage of coil for a relay); - under component similar enter a cross if relevant.
- Box 2; 3 and 4** As per QPL entry; otherwise, an explanation of the changes must be supplied.
- Box 5** Will show the ESCC Generic and Detail specifications, including issue number and revision letter, current at the time the tests reported were performed. If the specifications are different from those current on the date of the application, see Box 6.
- Box 6** Will show the deviations from the Generic and Detail Specifications listed in Box 5, in particular deviations from testing. In case of deviations this must be listed in Box 15. In case the referenced specification in Box 5 have currently a different issue and/or revision indicate also whether the test data deviates or not from such current documents.
- Box 7** Must reference the report(s) supplied in support of the application.
- Box 8** Should provide the details of procurement to the full ESCC System, documentation of all of which should already have been delivered to the ESCC Executive under the terms of the relevant Generic Specification. An appropriate table has been drawn in this box.
- Box 9** If the PID evolved after the Original Qualification or after the last Extension of Qualification, adequate details of such evolution shall be provided together with the reasons for the changes. Major changes shall be clearly marked.
- Box 10** Identify the current PID issue status, date and actual date of verification. The date of verification of the current PID should be arranged as close as possible to the required date of extension.
- Box 11** This box can be completed only after a physical visit to the plant to confirm that no unexplained changes occurred and that the practices, procedures, material, etc. used in manufacturing the components are as described in the PID. This survey shall be carried out in accordance with the requirements of ESCC Basic Specification No. 20200 and its findings shall be recorded.
- Box 12** Provide details of, or reference to, any Destructive Physical Analysis (DPA) and Failure Analysis reports as well as any Nonconformance(s) (NCCS) occurred during the qualification validity period, stating if established corrective action have produced satisfactory results.
- Box 13** Enter only the name of the Executive Member (i.e., CNES, DLR, ESTEC, etc.) and the signature of the responsible Executive Coordinator.
- Box 14** To be used when there is a need to expand any of the boxes from 1 through 12. Identify box affected and reference the Box 14 in the relevant Box. Box 14 can be broken into 14a, 14b, etc. if several boxes have to be expanded.
- Box 15** Fill in Table as requested.
- Box 16** Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.
- Box 17** All Executive Manager recommendations on the application itself, special conditions or restrictions, modifications of the QPL or QML entry, letters to the manufacturer, etc. shall be entered clearly in Box 19, signed by the representative for ESA, and dated.
- Box 18** Fill in Table as requested.
- Box 19** Confidential Details of PID changes including those of a confidential nature, shall be provided.
- Box 20** State noncompliance with reference to specification(s) and paragraph(s). To simplify reference in Box 16 each nonconformance shall be sequentially numbered. If relevant state 'None'.
- Box 21** Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.
- Box 22** Additional Comments.